WIRE BONDING APPARATUS HAVING ACTUATED FLAME-OFF WAND

Abstract

A wire bonding machine is provided which includes a bond head including a wire bonding tool adapted to feed a wire for bonding to bonding locations. The wire bonding machine also includes an electronic flame-off wand configured to heat an end portion of the wire extending through the bonding tool to form a free-air ball for bonding. The electronic flame-off wand is vertically actuatable relative to a support structure of the electronic flame-off wand.